



APTEP1.40CP2DC (formerly APTLTD.40CP2DC)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Gerald A. Hutchinson, et. al
Appl. No. : 10/788,905
Filed : February 26, 2004
For : PREFORM MOLDS
INCORPORATING HIGH HEAT
CONDUCTIVITY MATERIAL
Examiner : Timothy W. Heitbrink
Group Art Unit : 1722

RESPONSE TO AUGUST 1, 2006 OFFICE ACTION

Mail Stop Amendment
U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Response is being filed after the Office Action mailed August 1, 2006 ("Office Action"). Applicants request the Examiner to reconsider the above-identified patent application in view of the following remarks.

Listing of Claims begins on page 2 of this paper.

Remarks begin on page 6 of this paper.